

**$V_{DSM}$**  = 5200 V  
 **$I_{TAVM}$**  = 2760 A  
 **$I_{TRMS}$**  = 4340 A  
 **$I_{TSM}$**  = 42000 A  
 **$V_{TO}$**  = 1.00 V  
 **$r_T$**  = 0.225 mΩ

# Phase Control Thyristor

**5STP 25L5200**

Doc. No. 5SYA1008-03 Sep. 01

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

## Blocking

Part Number	5STP 25L5200	5STP 25L5000	5STP 25L4600	Conditions
$V_{DSM}$ $V_{RSM}$	5200 V	5000 V	4600 V	$f = 5 \text{ Hz}, t_p = 10\text{ms}$
$V_{DRM}$ $V_{RRM}$	4400 V	4200 V	4000 V	$f = 50 \text{ Hz}, t_p = 10\text{ms}$
$V_{RSM1}$	5700 V	5500 V	5100 V	$t_p = 5\text{ms}$ , single pulse
$I_{DSM}$	$\leq 400 \text{ mA}$		$V_{DSM}$	
$I_{RSM}$	$\leq 400 \text{ mA}$		$V_{RSM}$	$T_j = 125^\circ\text{C}$
$dV/dt_{crit}$	2000 V/ $\mu\text{s}$		Exp. to $0.67 \times V_{DRM}$ , $T_j = 125^\circ\text{C}$	

$V_{DRM}/V_{RRM}$  are equal to  $V_{DSM}/V_{RSM}$  values up to  $T_j = 110^\circ\text{C}$

## Mechanical data

$F_M$	Mounting force	nom.	70 kN
		min.	63 kN
		max.	84 kN
a	Acceleration		
	Device unclamped		50 m/s <sup>2</sup>
	Device clamped		100 m/s <sup>2</sup>
m	Weight		1.45 kg
D <sub>s</sub>	Surface creepage distance		36 mm
D <sub>a</sub>	Air strike distance		15 mm

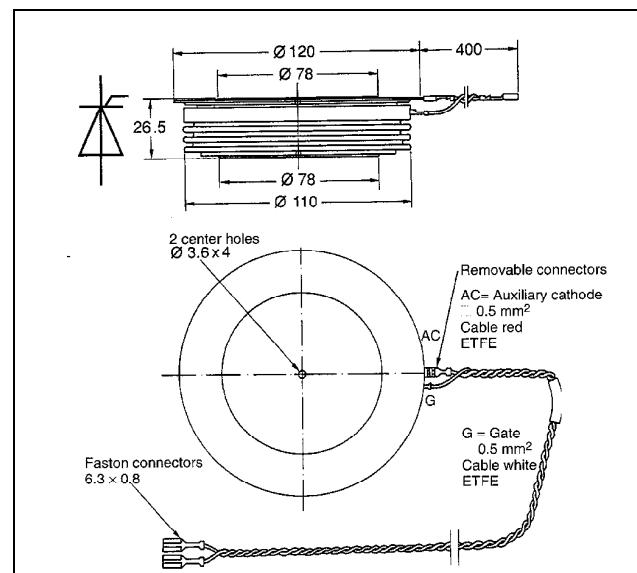


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## On-state

$I_{TAVM}$	Max. average on-state current	2760 A	Half sine wave, $T_C = 70^\circ\text{C}$	
$I_{TRMS}$	Max. RMS on-state current	4340 A		
$I_{TSM}$	Max. peak non-repetitive	42000 A	$t_p = 10 \text{ ms}$	$T_j = 125^\circ\text{C}$ After surge: $V_D = V_R = 0\text{V}$
	surge current	45000 A	$t_p = 8.3 \text{ ms}$	
$I^2t$	Limiting load integral	8820 $\text{kA}^2\text{s}$	$t_p = 10 \text{ ms}$	
		8404 $\text{kA}^2\text{s}$	$t_p = 8.3 \text{ ms}$	
$V_T$	On-state voltage	1.70 V	$I_T = 3000 \text{ A}$	$T_j = 125^\circ\text{C}$
$V_{T0}$	Threshold voltage	1.00 V	$I_T = 1300 - 4000 \text{ A}$	
$r_T$	Slope resistance	0.225 mΩ		
$I_H$	Holding current	50-125 mA	$T_j = 25^\circ\text{C}$	
		15-60 mA	$T_j = 125^\circ\text{C}$	
$I_L$	Latching current	100- mA	$T_j = 25^\circ\text{C}$	
		75-250 mA	$T_j = 125^\circ\text{C}$	

## Switching

$di/dt_{crit}$	Critical rate of rise of on-state current	250 A/μs	Cont. $f = 50 \text{ Hz}$	$V_D \leq 0.67 \cdot V_{DRM}, T_j = 125^\circ\text{C}$
		500 A/μs	60 sec. $f = 50\text{Hz}$	$I_{TRM} = 3000 \text{ A}$ $I_{FG} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$
$t_d$	Delay time	$\leq 3.0 \mu\text{s}$	$V_D = 0.4 \cdot V_{DRM}$	$I_{FG} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$
$t_q$	Turn-off time	$\leq 700 \mu\text{s}$	$V_D \leq 0.67 \cdot V_{DRM}$ $dv_D/dt = 20\text{V}/\mu\text{s}$	$I_{TRM} = 3000 \text{ A}, T_j = 125^\circ\text{C}$ $V_R > 200 \text{ V}, di_T/dt = -5 \text{ A}/\mu\text{s}$
$Q_{rr}$	Recovery charge	min	5500 μAs	
		max	7500 μAs	

## Triggering

$V_{GT}$	Gate trigger voltage	2.6 V	$T_j = 25^\circ$
$I_{GT}$	Gate trigger current	400 mA	$T_j = 25^\circ$
$V_{GD}$	Gate non-trigger voltage	0.3 V	$V_D = 0.4 \times V_{DRM}$
$I_{GD}$	Gate non-trigger current	10 mA	$V_D = 0.4 \times V_{DRM}$
$V_{FGM}$	Peak forward gate voltage	12 V	
$I_{FGM}$	Peak forward gate current	10 A	
$V_{RGM}$	Peak reverse gate voltage	10 V	
$P_G$	Gate power loss	3 W	

**Thermal**

$T_{j\max}$	Max. operating junction temperature range	125 °C	
$T_{stg}$	Storage temperature range	-40...140 °C	
$R_{thJC}$	Thermal resistance junction to case	14 K/kW	Anode side cooled
		14 K/kW	Cathode side cooled
		7 K/kW	Double side cooled
$R_{thCH}$	Thermal resistance case to heat sink	3 K/kW	Single side cooled
		1.5 K/kW	Double side cooled

**Analytical function for transient thermal impedance:**

$$Z_{thJC}(t) = \sum_{i=1}^n R_i(1 - e^{-t/\tau_i})$$

i	1	2	3	4
$R_i(K/kW)$	4.7	0.853	1.07	0.49
$\tau_i(s)$	0.4787	0.0824	0.0104	0.0041

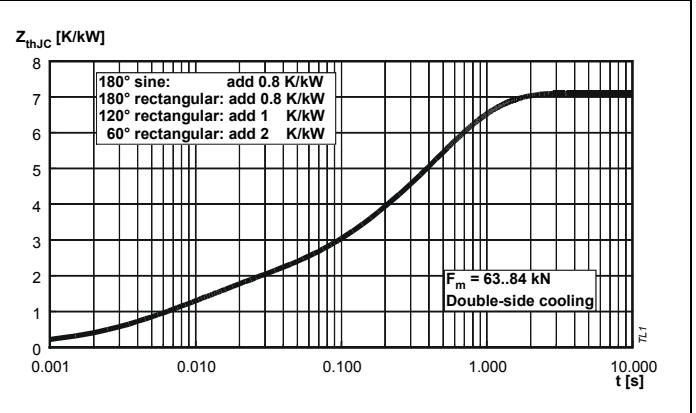


Fig. 1 Transient thermal impedance junction to case.

**On-state characteristic model:**

$$VT = A + B \cdot iT + C \cdot \ln(iT+1) + D \cdot \sqrt{IT}$$

Valid for  $i_T = 500 - 10000$  A

A	B	C	D
-0.006184	0.00022	0.173291	-0.006405

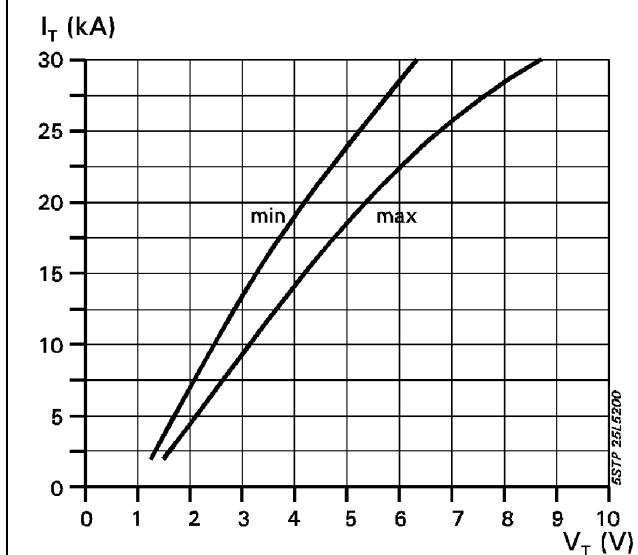
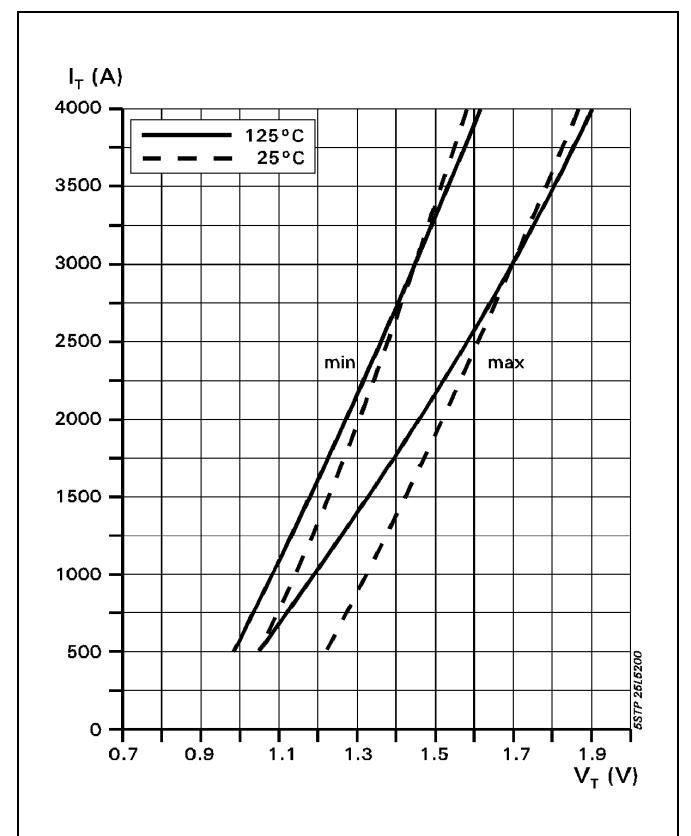
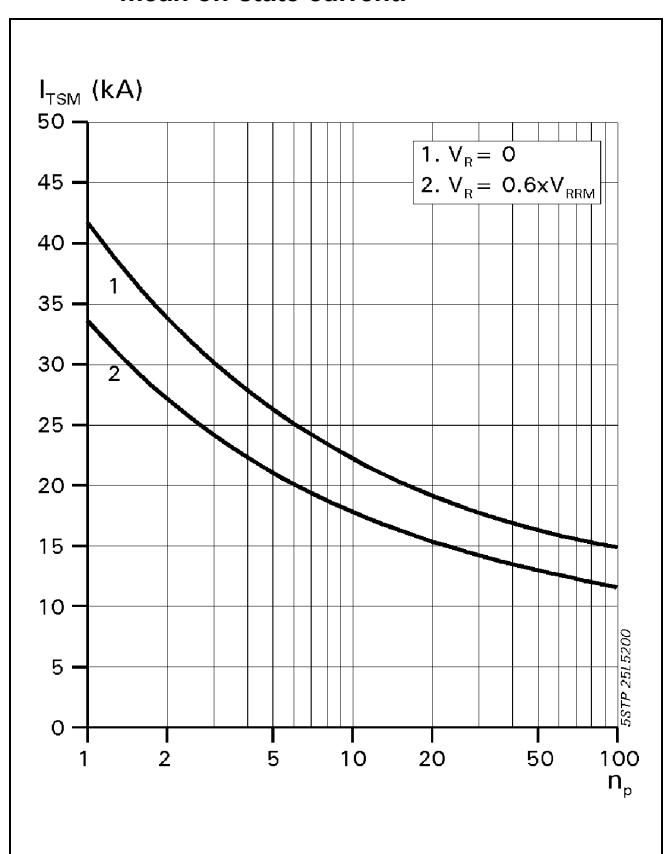
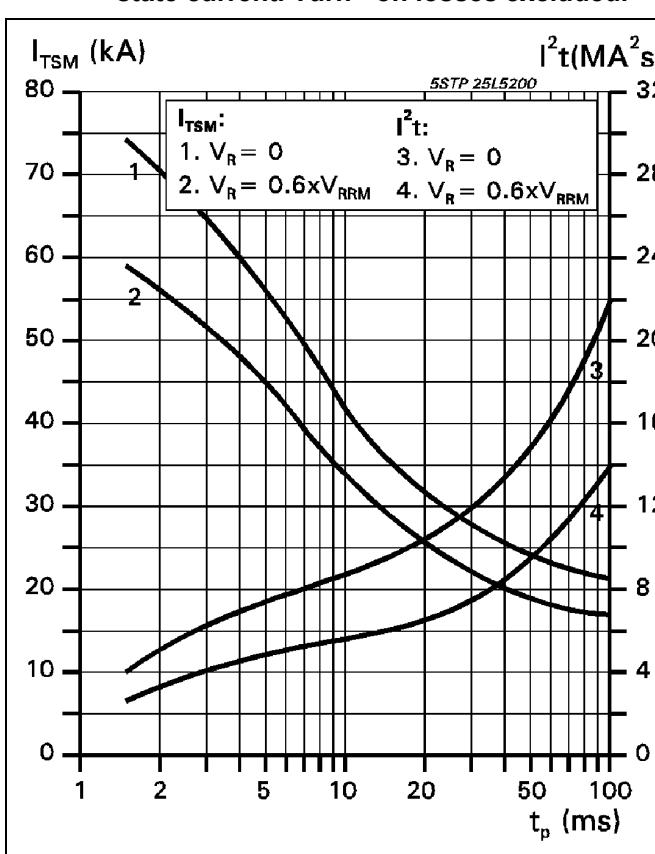
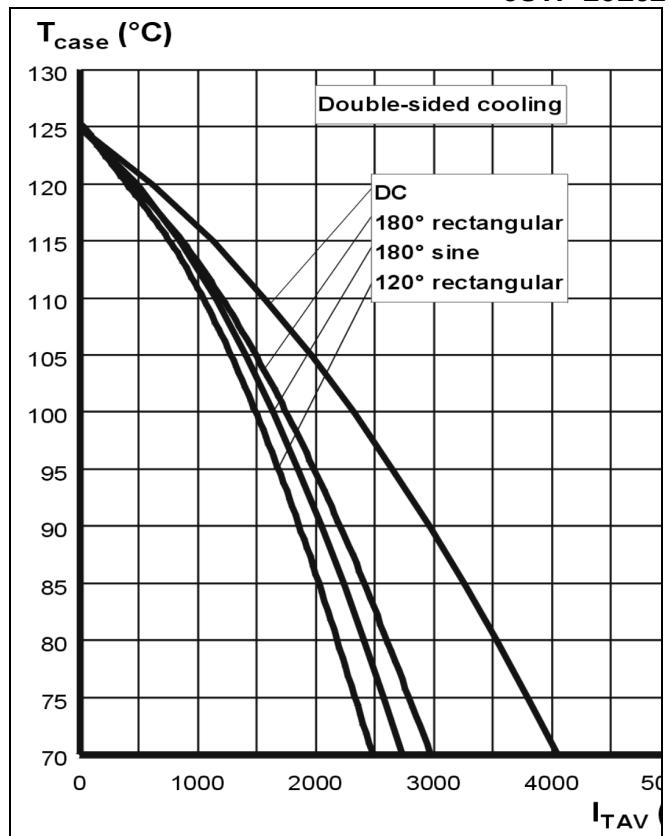
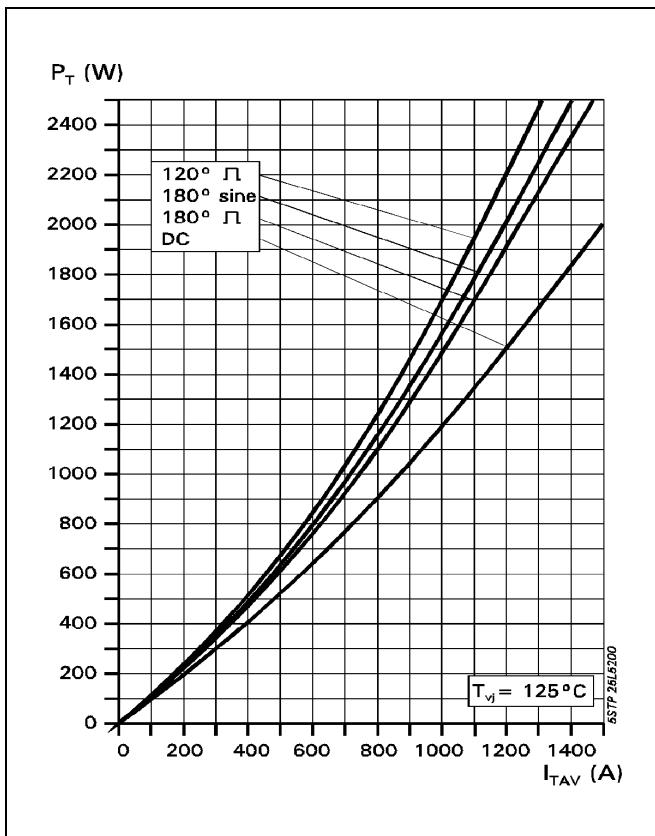
Fig. 2 On-state characteristics.  
 $T_j=125^\circ\text{C}$ , 10ms half sine

Fig. 3 On-state characteristics.



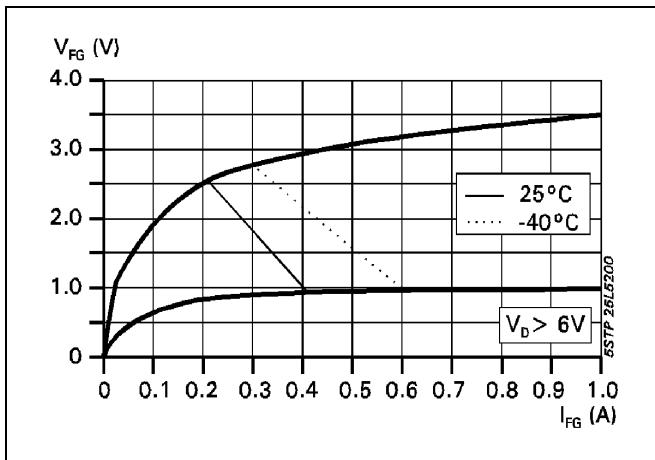


Fig. 8 Gate trigger characteristics.

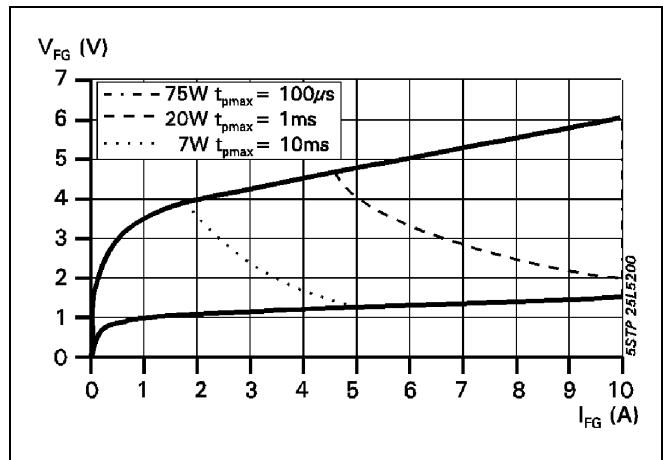


Fig. 9 Max. peak gate power loss.

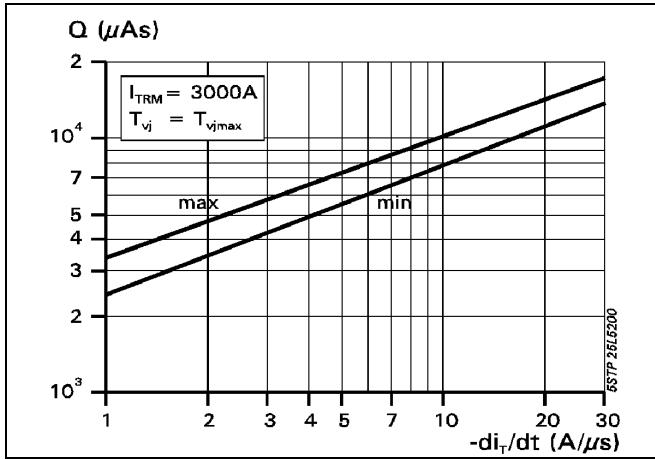


Fig. 10 Recovery charge vs. decay rate of on-state current.

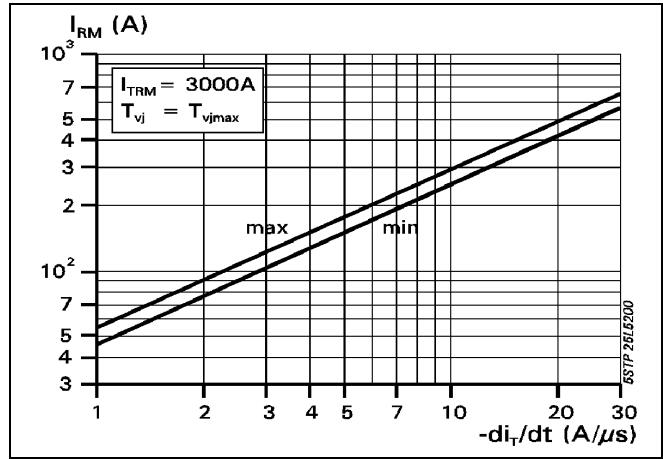
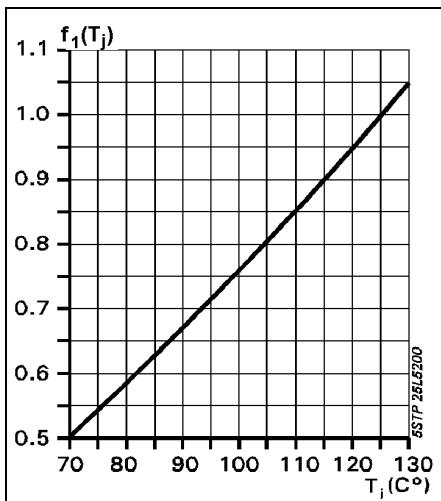
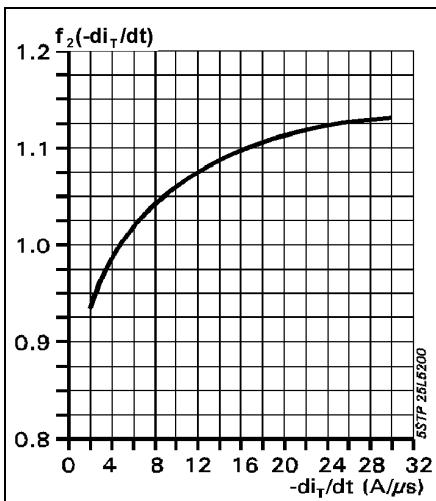
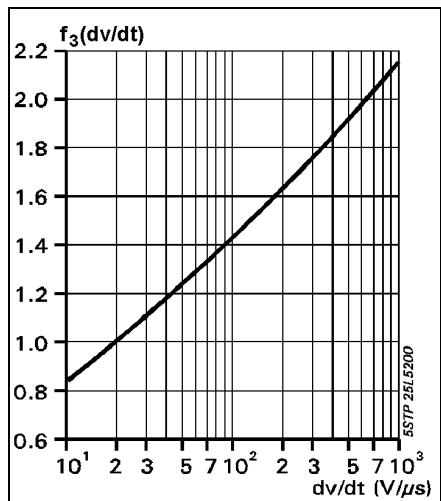


Fig. 11 Peak reverse recovery current vs. decay rate of on-state current.

## Turn - off time, typical parameter relationship.

Fig. 12  $t_q/t_{q1} = f_1(T_j)$ Fig. 13  $t_q/t_{q1} = f_2(-di_T/dt)$ Fig. 14  $t_q/t_{q1} = f_3(dv/dt)$ 

$$t_q = t_{q1} \cdot f_1(T_j) \cdot f_2(-di_T/dt) \cdot f_3(dv/dt)$$

$t_{q1}$  : at normalized values (see page 2)  
 $t_q$  : at varying conditions

## Turn-on and Turn-off losses

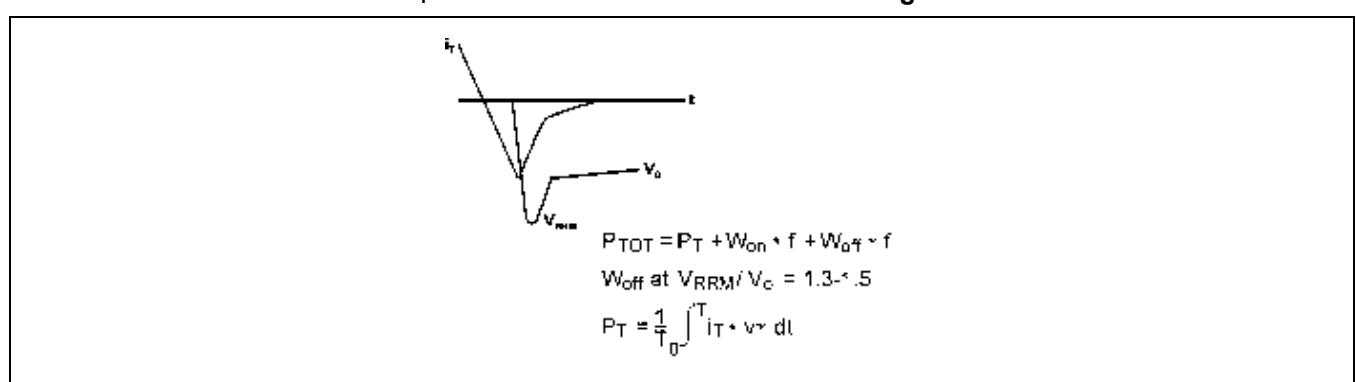
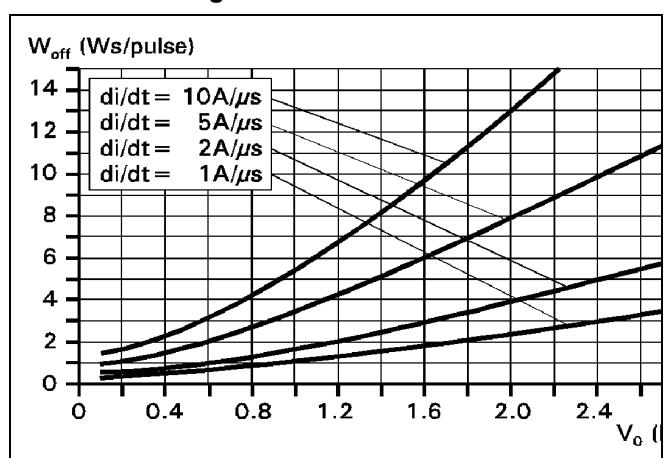
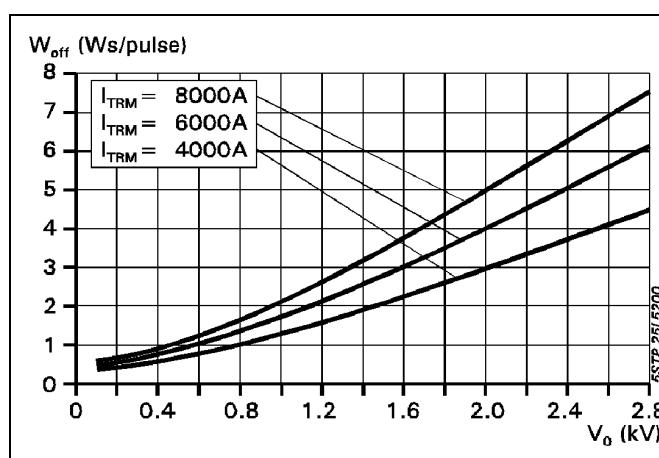
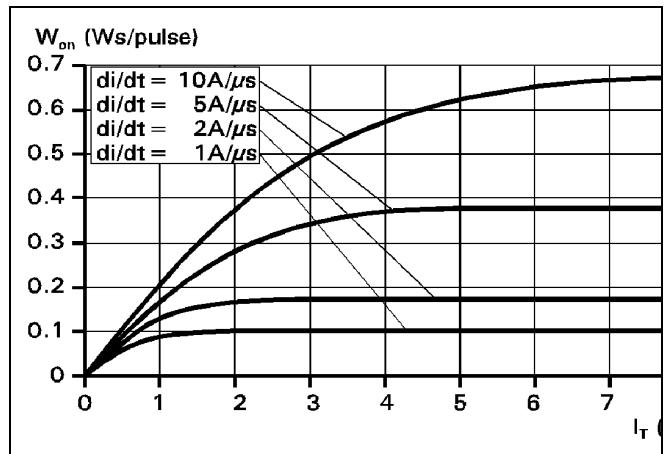
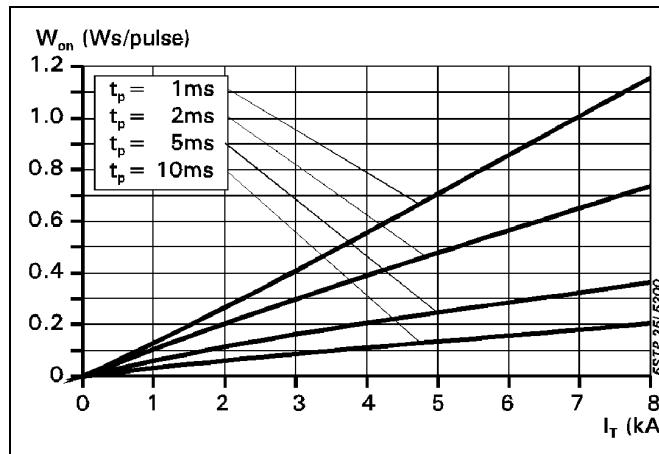


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